



#21/E
Amend de
Y Robinson
7/24/03
Docket No.: M4065.0196/P196
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Shane P. Leiphart

Application No.: 09/371,955

Group Art Unit: 2811

Filed: August 11, 1999

Examiner: D. Kang

For: ENHANCED BARRIER LINER
FORMATION FOR VIAS

AMENDMENT

Box Non-Fee Amendment
Commissioner for Patents
Washington, DC 20231

Dear Sir:

In response to the Office Action dated January 17, 2003 (Paper No. 20), please amend the above-identified U.S. patent application as follows:

In the Specification:

Please replace the respective portions of the specification with the amended portions as follows:

At page 7, first full paragraph:

E1
In this embodiment, a dual-layer lining comprised of a titanium aluminide layer 16 and a titanium nitride layer 17, in that sequence, is formed on the sidewalls and bottom of the via hole 200. The titanium aluminide layer 16 is preformed before the titanium nitride layer is deposited thereon. Exemplary techniques of this invention for preforming a titanium aluminide are described in greater detail in discussions set out below referencing

RECEIVED
APR 17 2003
TECHNOLOGY CENTER 2800